



Compound Semiconductor Materials Japan TC Chapter Meeting

Japan Standards Spring Meetings 2025

Monday, June 30, 2025

Room 1, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

2:00 PM – 5:00 PM JST

AGENDA

1 Welcome/Call to Order

- 1.1 Introduction
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

- 3.1 Japan Regional Standards Committee (JRSC)
- 3.2 Global Coordinating Subcommittee (GCS)
- 3.3 Europe TC Chapter
- 3.4 North America TC Chapter
- 3.5 China TC Chapter

4 Staff Report

5 Ballot Review

- 5.1 Doc.#7211A, Line Item Revision to SEMI M92-0824, Specification for 4H-SiC Homoepitaxial Wafer

6 Subcommittee & Task Force Reports

- 6.1 Silicon Carbide Substrate Liaison Task Force
- 6.2 SiC Epitaxial Wafer Liaison Task Force



7 Old Business

7.1 Project Period Review

7.2 5-year Review

8 New Business

9 Action Item Review

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20220119-03	Silicon Carbide Substrate Liaison TF leaders and SiC Epitaxial Wafer liaison TF leaders	To confirm the contents of Document #6693, 6767-9 and their ballot schedule and share them to the JA TF members and hold meetings as necessary.
CSM_20240521-01	SEMI Staff	To send Doc.#7211 Line Item 3-5 adjudication results to the ISC A&R SC for procedural review.
CSM_20240521-02	CSM_20240521-01	To have an explanatory session for Connect@SEMI.

9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>

10 Next Meeting and Adjournment

10.1 The next meeting is scheduled for <date> at <event/location>.